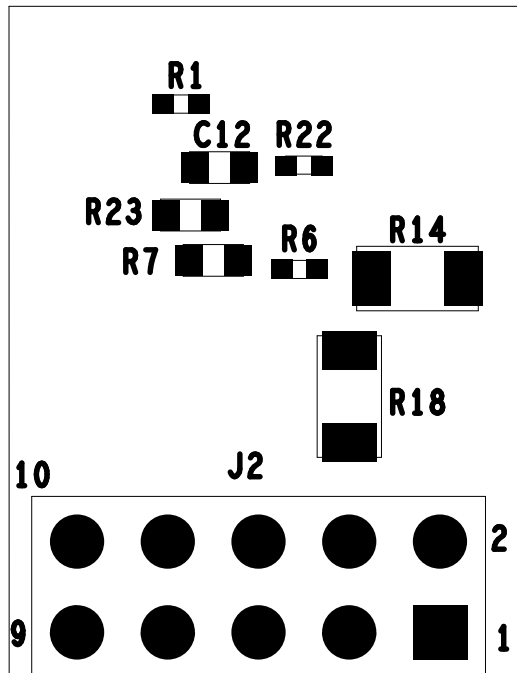


CURRENT SENSE BOARD

DATE: 03/08/2015

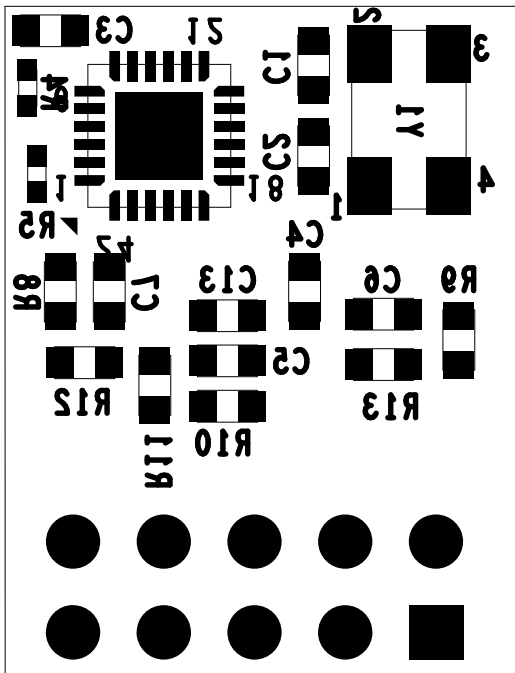
ASSEMBLY TOP



CURRENT SENSE BOARD

DATE: 03/08/2015

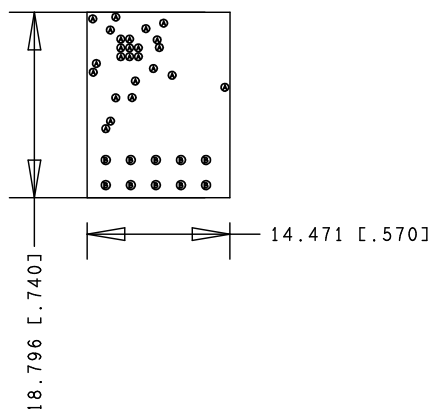
ASSEMBLY BOTTOM



CURRENT SENSE BOARD

DATE: 03/08/2015

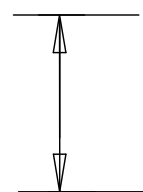
FAB_DRAWING



NOTES:

1. ALL ARTWORK PATTERNS ARE VIEWED FROM THE TOP.
2. PLATING FINISH METHOD SHALL BE HASL
3. SOLDER MASK OVER BARE COPPER (SMOBC) SHALL BE ON BOTH SIDES.
4. MASK COLOUR IS GREEN AND TYPE IS LPI
5. BOARD THICKNESS IS 1.6 MM
6. COPPER THICKNESS FOR OUTER LAYERS IS 35 MICRONS
7. PCB MATERIAL IS FR4
8. STACKUP SPECIFICATIONS IS AS FOLLOWS
9. SIGNAL TRACE WIDTH 8 MILS POWER TRACEWIDTH 20 MILS (MIN 11 MILS)
10. IF VIA IN PAD (VIP) SHOULD BE FILLED AND PLATTED WITH PLANNER

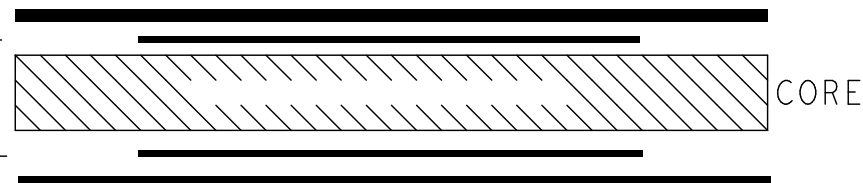
62.992 MILS
(1.6 MM)



LAYER 1-TOP

LAYER 2-BOT

STACKUP INFO



DRILL CHART: TOP to BOTTOM

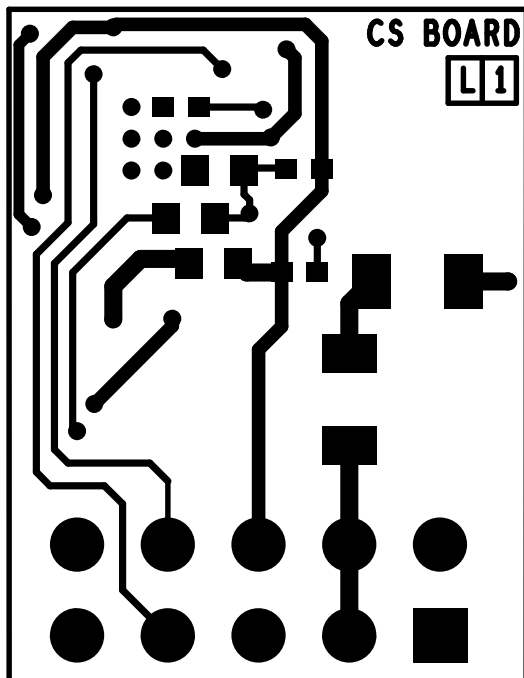
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+3.0 / -3.0	PLATED	25
•	40.0	+0.0 / -0.0	PLATED	10

CURRENT SENSE BOARD

DATE: 03/08/2015

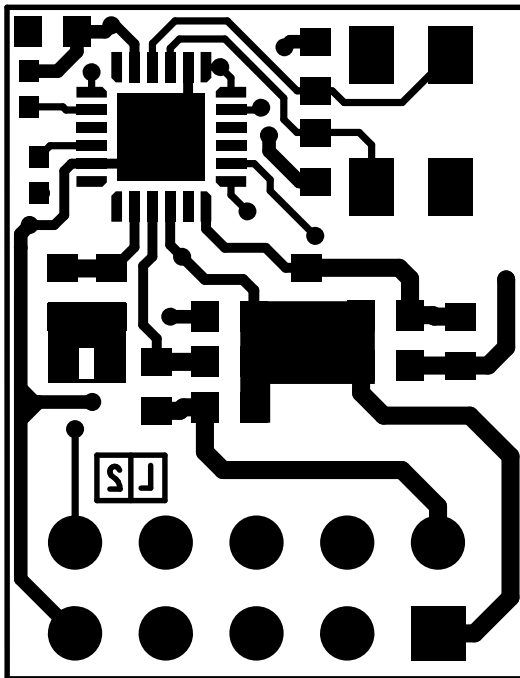
L01_TOP



CURRENT SENSE BOARD

DATE: 03/08/2015

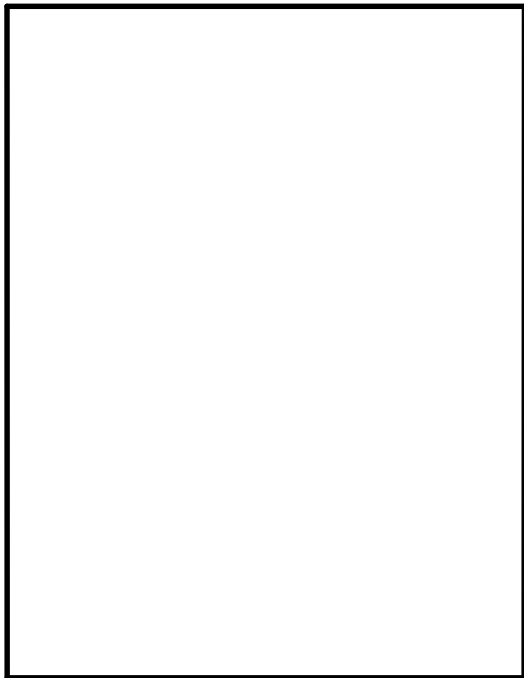
L02_BOTTOM



CURRENT SENSE BOARD

DATE: 03/08/2015

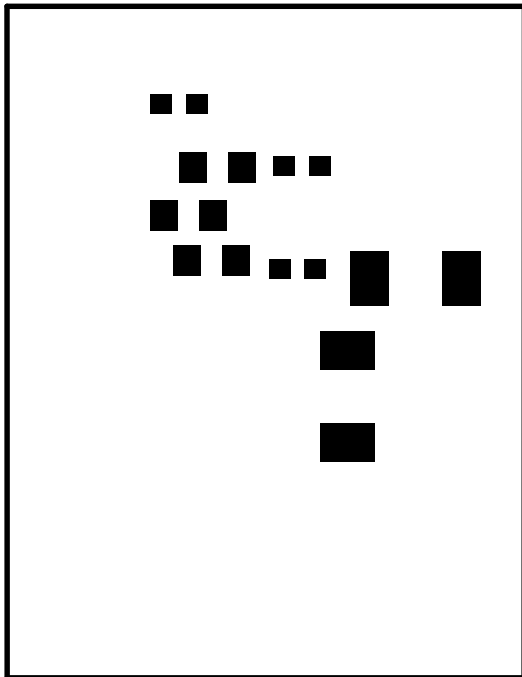
OUTLINE



CURRENT SENSE BOARD

DATE: 03/08/2015

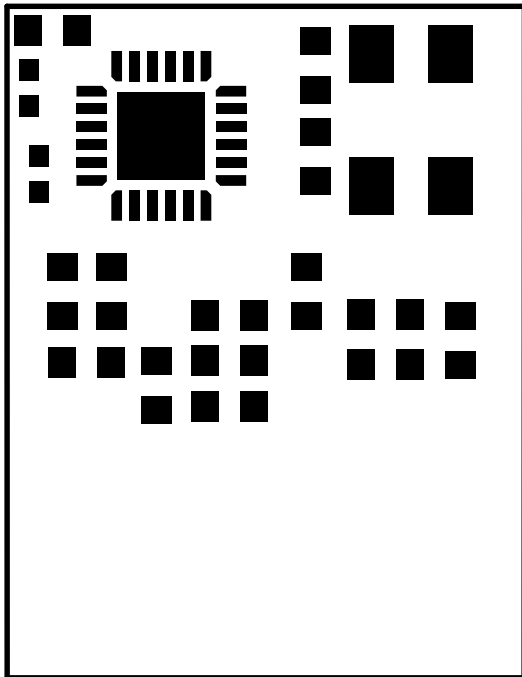
PASTEMASK TOP



CURRENT SENSE BOARD

DATE: 03/08/2015

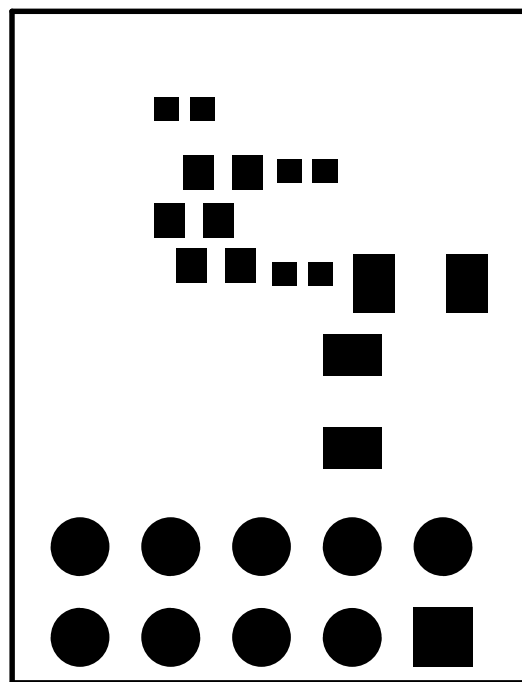
PASTEMASK BOTTOM



CURRENT SENSE BOARD

DATE: 03/08/2015

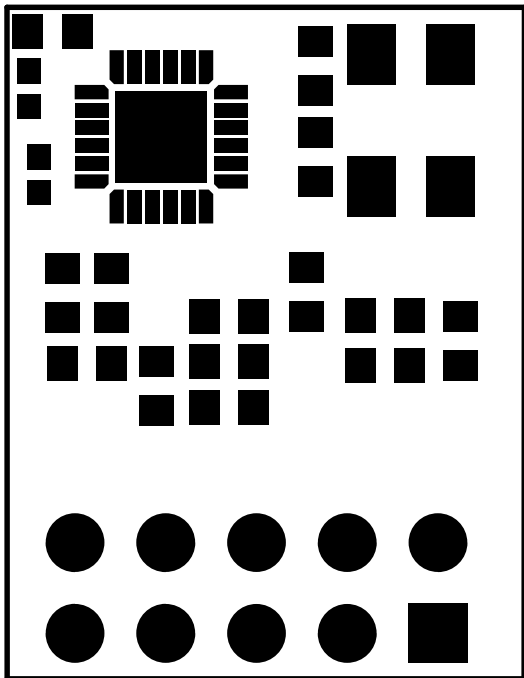
SOLDERMASK TOP



CURRENT SENSE BOARD

DATE: 03/08/2015

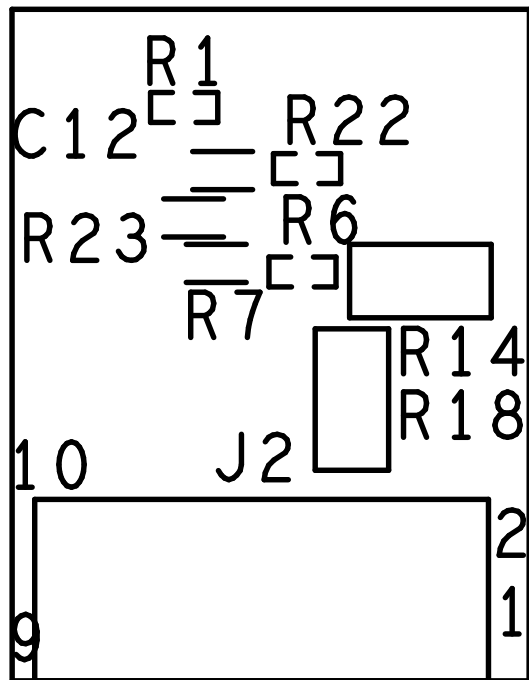
SOLDERMASK BOTTOM



CURRENT SENSE BOARD

DATE: 03/08/2015

SILKSCREEN TOP



CURRENT SENSE BOARD

DATE: 03/08/2015

SILKSCREEN BOTTOM

